IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: CHUNG, Ching-Yao; SUNG, Nai-Yin; CHEN, Yen-Hao

SERIAL NO.:

FILED:

Herewith

TITLE: POWER SUPPLY LAYOUT FOR AN INTEGRATED CIRCUIT

PRELIMINARY AMENDMENT

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

Sir:

In conjunction with the filing of the present application, and prior to an initial Official Action on this matter, please amend the above-identified application as follows:

Preliminary Amendment: SPECIFICATION AMENDMENTS

In Paragraphs [0017] to [0021], please amend the paragraphs as follows:

[0017] Other objectives and advantages of the present invention will become apparent upon reading the following description and upon reference to the accompanying drawings in which:

[0018] FIG. 1 is a schematic diagram of an integrated circuit according to the prior art;

[0019] FIG. 2 is a schematic diagram of an integrated circuit according to the first embodiment of the present invention;

[0020] FIG. 3 is a schematic diagram of an integrated circuit according to the second embodiment of the present invention; and.

[0021] FIG. 4 is a schematic diagram of an integrated circuit according to the third embodiment of the present invention.

IN THE ABSTRACT

On page 13, please amend the Abstract as follows:

A power supply layout for an integrated circuit comprises has a plurality of power pads, a plurality of ground pads, a plurality of first-type conductive wires directly connected to the power pad, a plurality of second-type conductive wires directly connected to the ground pad, and a core circuit electrically connected to the first-type and the second-type conductive wires for acquiring the operational power. The integrated circuit is made of a plurality of metal layers, wherein the first-type